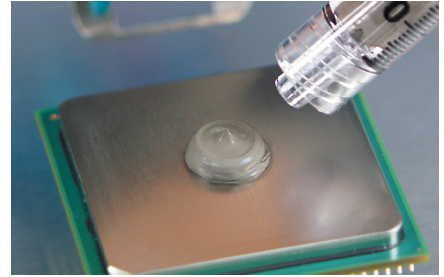
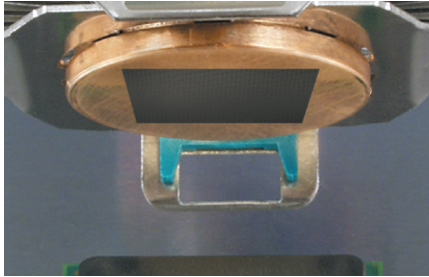


# TIC™ - Thermal Interface Compound

## Thermally Conductive Grease Compounds

Bergquist's line of thermally conductive thermal interface compounds will flow under assembly pressure to wet-out the thermal interface surfaces and produce very low thermal impedance. TIC products are

designed for use between a high-end computer processor and a heat sink or other high watt density applications.



### Features

The TIC portfolio has diverse thermal and electrical characteristics. Key criteria when selecting TIC products include:

- Viscosity
- Volume resistivity
- Thermal conductivity
- Thermal performance
- Filler size

### Benefits

TIC products are ideal for high watt density applications. Primary benefits include:

- Low interfacial resistance
- Low thermal impedance
- Resists dripping
- Ideally suited to screen printing applications
- No post "cure" conditioning required

### Options

TIC products can be obtained with application-specific options such as:

- Containers

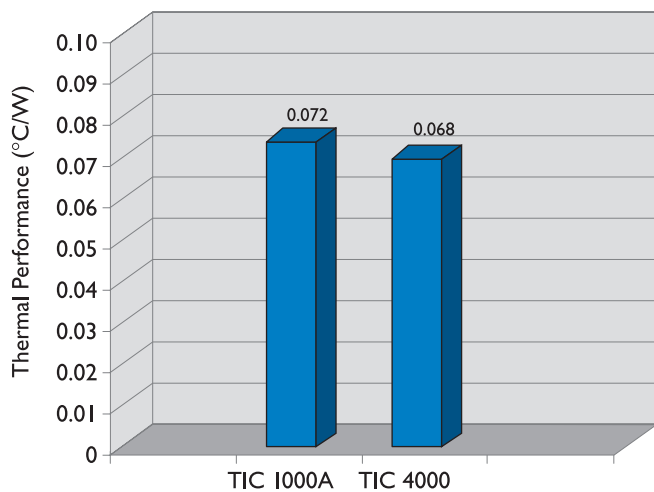
### Applications

TIC has a variety of applications such as:

- CPU
- GPU
- IGBT
- High power density applications

## Comparison Data and FAQ's

High Performance CPU Application, 38 X 38 mm



**Q: What is the best fastening method for a TIC interface?**

**A:** A constant-pressure fastener is preferred when using TIC for high performance applications. The constant pressure from a clip or spring washer will ensure adequate pressure is being applied with varying bond line thickness.

**Q: How should the TIC be applied?**

**A:** Screenprinting the TIC is a fast, low-cost method that delivers a consistent and accurate amount of material on each application. Alternate methods include stenciling, pin transfer and needle dispensing.

**Q: Will the grease stay in the interface?**

**A:** All the TIC materials were specifically designed to resist pump-out of the interface, even after many hours of thermal and power cycling.